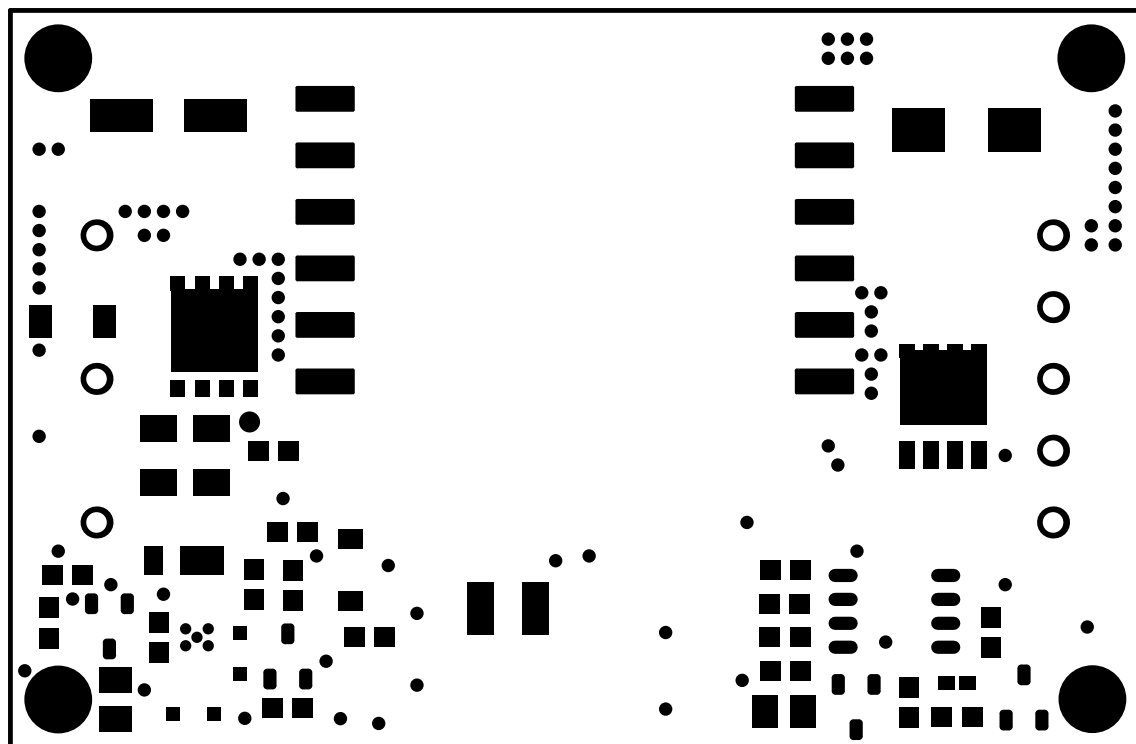
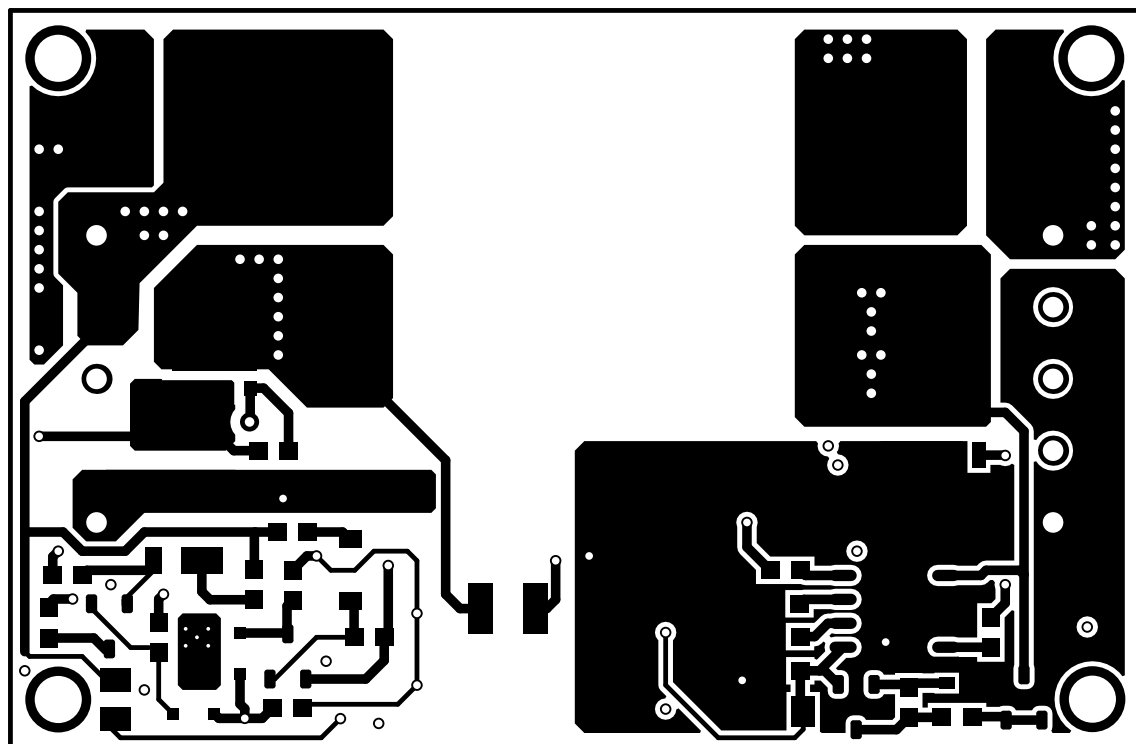


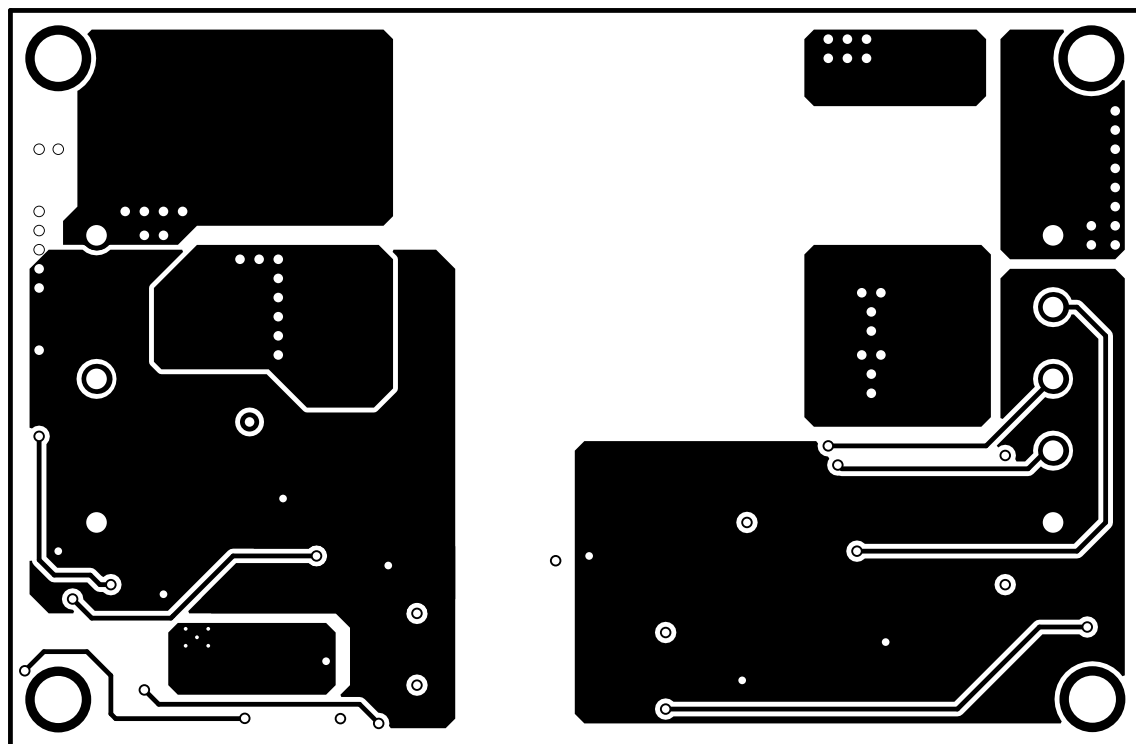
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: N/A | | |
| PLOT NAME = Top Overlay | GENERATED : 8/4/2017 | 4:38:54 PM | TEXAS INSTRUMENTS |



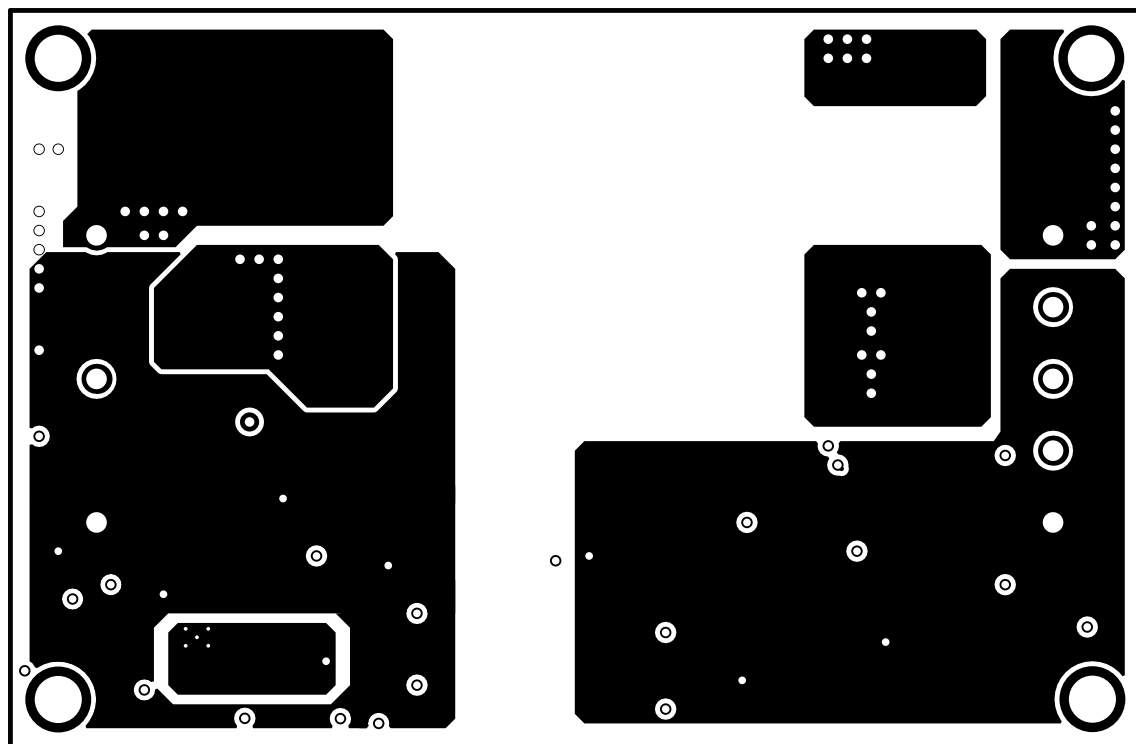
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: N/A | | |
| PLOT NAME = Top Solder Mask | GENERATED : 8/4/2017 | 4:38:55 PM | TEXAS INSTRUMENTS |



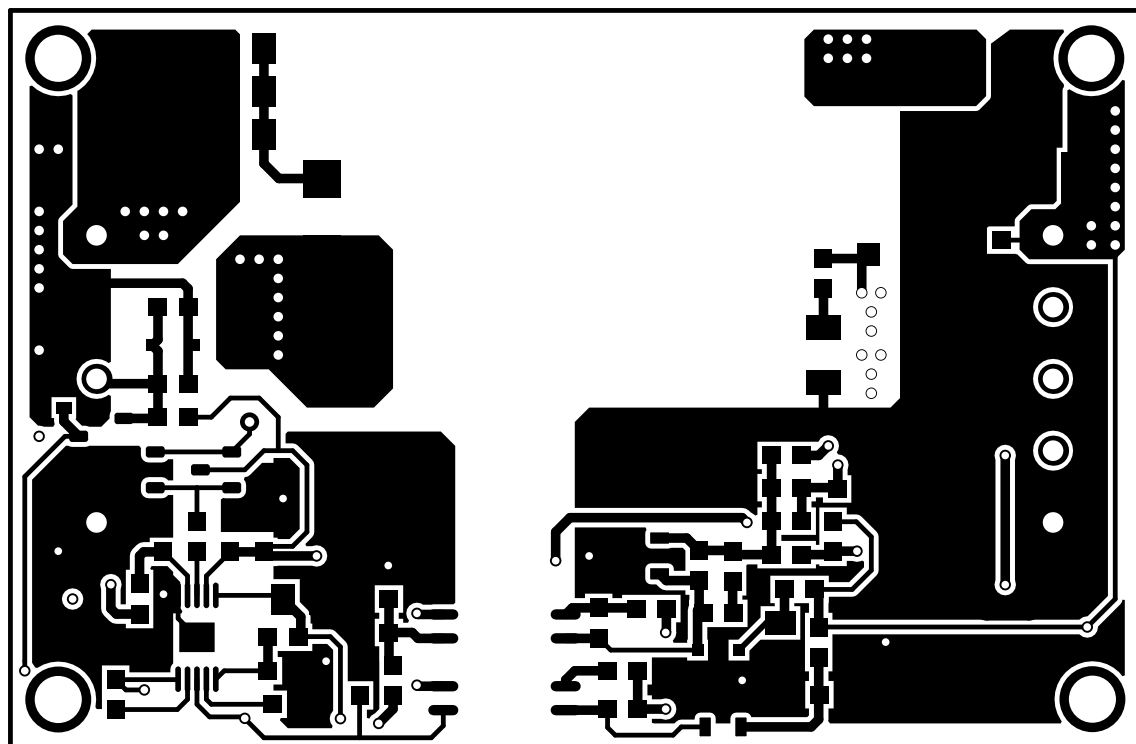
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: N/A | | |
| PLOT NAME = Top Layer | GENERATED : 8/4/2017 | 4:38:56 PM | TEXAS INSTRUMENTS |



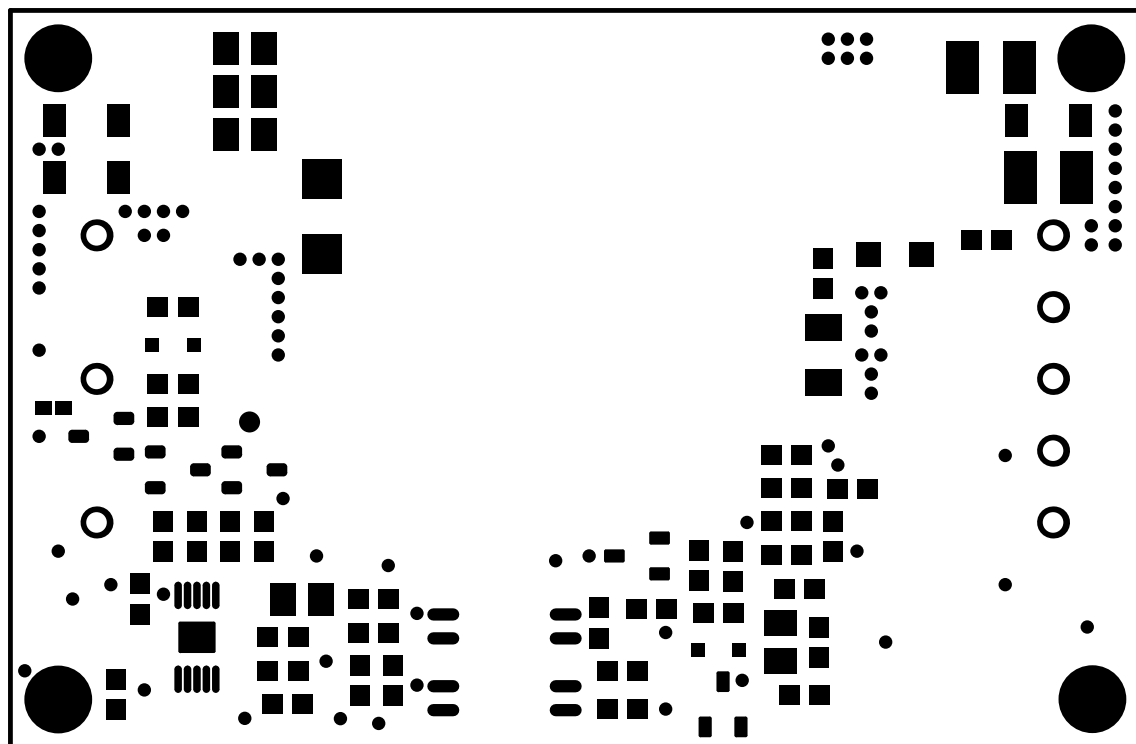
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = | TID #: N/A | | |
| PLOT NAME = Signal Layer 1 | GENERATED : 8/4/2017 | 4:38:57 PM | TEXAS INSTRUMENTS |



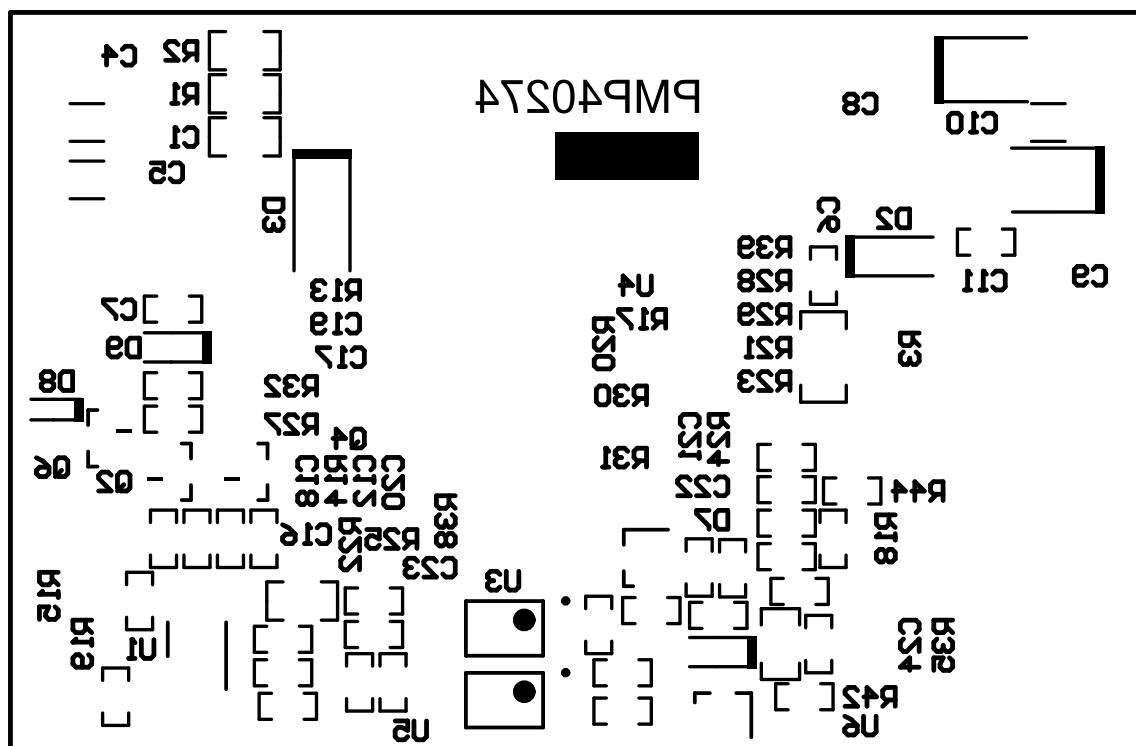
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = | TID #: N/A | | |
| PLOT NAME = Signal Layer 2 | GENERATED : 8/4/2017 | 4:38:57 PM | TEXAS INSTRUMENTS |



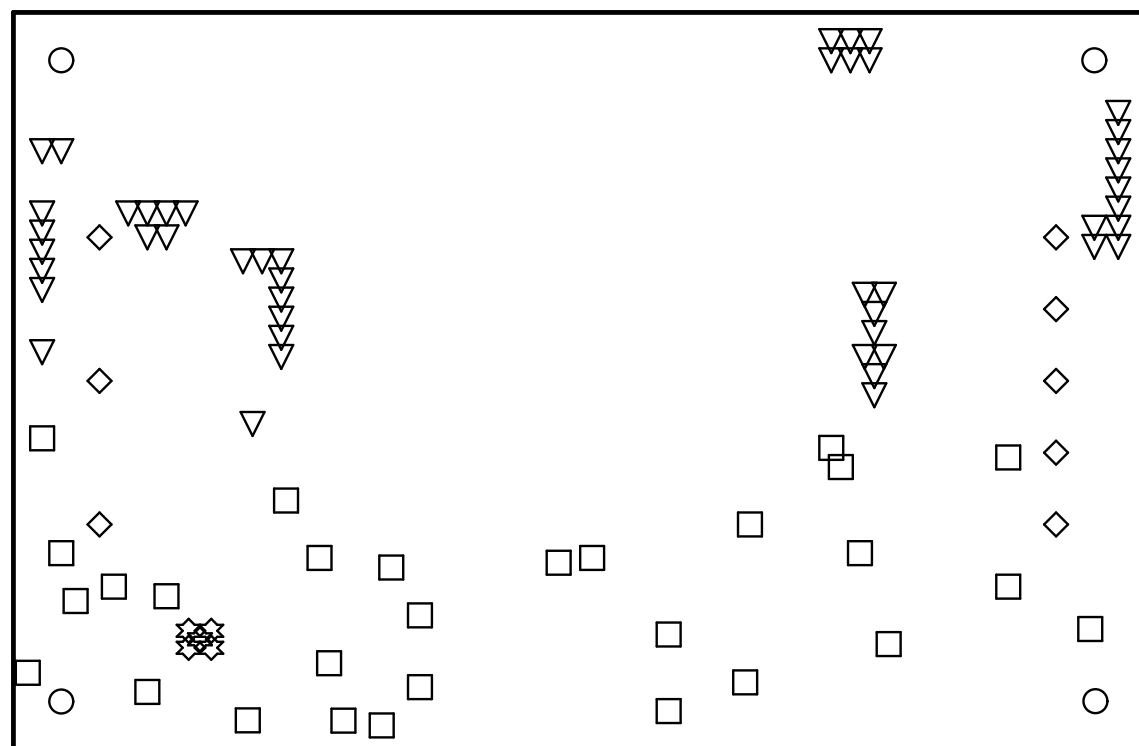
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: N/A | | |
| PLOT NAME = Bottom Layer | GENERATED : 8/4/2017 | 4:38:58 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: N/A | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 8/4/2017 4:38:59 PM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: N/A | | |
| PLOT NAME = Bottom Overlay | GENERATED : 8/4/2017 | 4:39:00 PM | TEXAS INSTRUMENTS |



| Symbol | Quantity | Finished Hole Size | Plated | Hole Type | Drill Layer Pair | Hole Tolerance |
|--------|----------|--------------------|--------|-----------|--------------------------|----------------|
| ⊛ | 5 | 7.87mil (0.200mm) | PTH | Round | Top Layer - Bottom Layer | |
| □ | 29 | 16.00mil (0.406mm) | PTH | Round | Top Layer - Bottom Layer | |
| ▽ | 47 | 20.00mil (0.508mm) | PTH | Round | Top Layer - Bottom Layer | |
| ◇ | 8 | 43.00mil (1.092mm) | PTH | Round | Top Layer - Bottom Layer | |
| ○ | 4 | 98.43mil (2.500mm) | PTH | Round | Top Layer - Bottom Layer | |
| | 93 Total | | | | | |

| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: N/A | | |
| PLOT NAME = Drill Drawing | GENERATED : 8/4/2017 | 4:39:01 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|---------------------------------|---------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP40274 | REV: E1 | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: N/A | | |
| PLOT NAME = Board Dimensions | GENERATED : 8/4/2017 4:39:02 PM | | TEXAS INSTRUMENTS |

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